

Leadframe Rework on Microsemi CQFP Packages

Thank you for your interest in Microsemi's CQFPs.

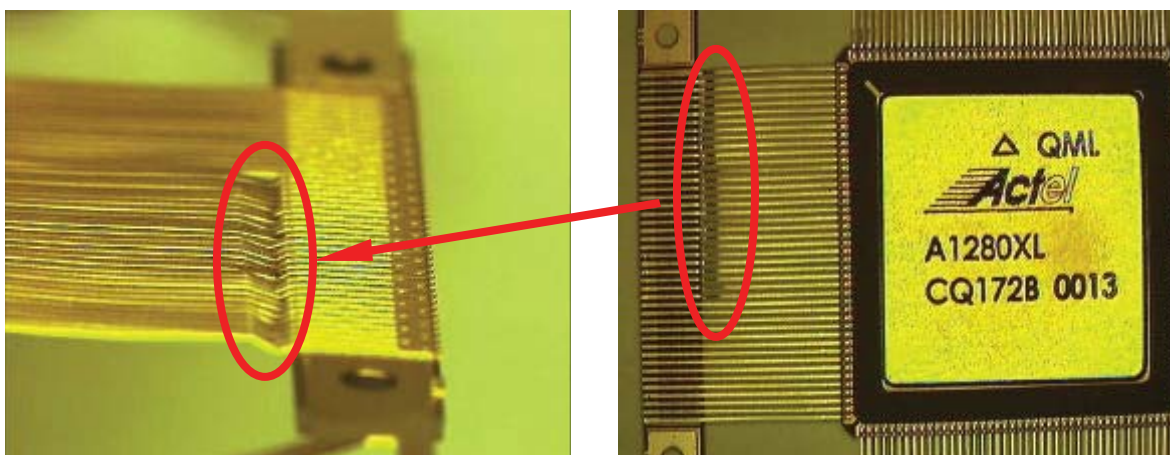
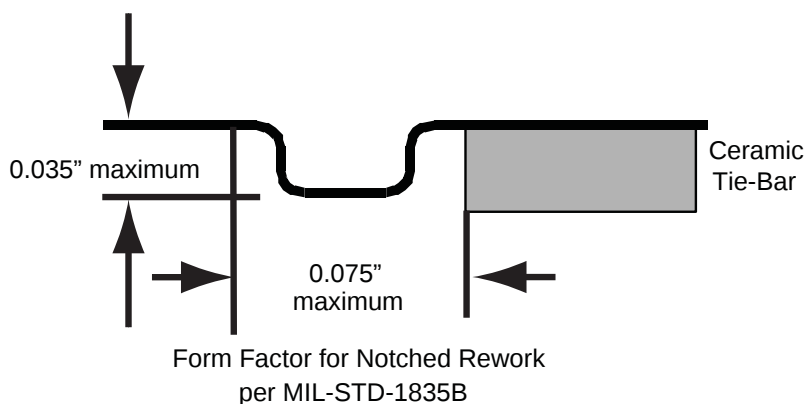
The following describes a notch that is put at the end of leads, near the ceramic leadframe during rework.

The standard leadframe rework is frequently mistaken as visual rejects like bent leads and scratches.

CQFP packages have straight leads that are very thin and narrow in width; therefore, the leads are easy to bend during the manufacturing process. To effectively straighten the bent leads at final visual inspection, Microsemi SoC Products Group (formerly Actel) implemented a procedure to mechanically put a notch at the end, near the ceramic leadframe (see picture). The form factor of this rework is clearly defined on MIL-STD-1835B, Notice 2, detail G on page 136 (see sketch), and note 11 on page 141.

The reworked leadframe will not affect the device programming and testing performed at customer site, and the reworked area must be removed prior to lead forming process.

Therefore, there shall be no concern on device form-fit factor, functionality, and reliability as the result of this rework.



Notched Lead Rework at the Edge of the Ceramic Leadframe